

PROCESS FOR PRODUCING MULTILAYER CIRCUIT BOARD

ABSTRACT OF THE DISCLOSURE

A process for making a multilayer wiring board includes the following steps of: laminating an electrically insulating resin substrate, having first and second surfaces and a metal layer formed on the first surface, onto a base material on which a predetermined wiring pattern is formed, so that the second surface of the resin substrate is adhered to the base material; removing a predetermined amount of the metal layer to form an opening at a position where a connection with the wiring pattern is to be provided; irradiating a laser beam toward the resin layer through the resin removed region to form a blind via hole having a diameter smaller than that of the opening, so that the wiring pattern is exposed at a bottom of the blind via hole; electroless plating to form an electroless plated film on the exposed wiring pattern, a side wall of the blind via hole, a step portion of the exposed resin layer, and at least a metal layer at a periphery of the opening; electro plating to form an electro plated film on the electroless plated film; and after the electro plating, etching the metal layer to form a predetermined wiring pattern.

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